

HSPA+ 模组 H330S



Quad-band
GSM/GPRS/EDGE

Quad-band HSPA/HSPA+

5.76Mbps HSUPA

21Mbps HSDPA

Internal TCP/IP & UDP/IP

Temperature Range
-40°C~+85°C

Analog and Digital Audio

FIBOCOM H330S LGA模块，采用业界领先的Intel平台，支持全球主要3G频段。为客户提供丰富的应用接口，包括USB2.0、UART、I2C、I2S，内置TCP/IP和UDP/IP协议栈，灵活性强，易于集成。

H330S LGA模块可应用于车载导航、安防监控、无线POS和远程医疗等工业领域，亦可应用于平板电脑和电子书等消费电子，满足用户对移动宽带的应用需求。



HSPA+ 模组 H330S



产品特性

- WCDMA: Band 1,2,5,8 or Band 1,8
- GSM/GPRS/EDGE: 850/900/1800/1900MHz
- or 900/1800MHz
- LGA 120pin 33.8 x 27.8 x 2.45mm
- Operating Temperature: -30 ~ +75°C
- Storage Temperature: -40 ~ +85°C
- Operating Voltage: DC 3.3V~4.2V, Typical 3.8V
- TX Power
UMTS/HSPA+ Class 3 (0.25W)
GSM 850/900 MHz Class 4 (2W)
GSM 1800/1900 MHz Class 1 (1W)
EDGE 850/900 MHz Class E2 (0.5W)
EDGE 1800/1900 MHz Class E2 (0.4W)
- AT Command Set: FIBOCOM proprietary AT commands/
GSM 07.05/GSM 07.07

数据特性

- UMTS/HSDPA/HSUPA 3GPP release 7
- HSUPA 5.76Mbps (Cat 6)
- HSDPA 21Mbps (Cat 14)/7.2Mbps (Cat 8)
- GSM 3GPP release 7
- EDGE (E-GPRS) Multi-slot class 33(296kbps DL,
236.8kbps UL)
- GPRS Multi-slot class 33(107kbps DL, 85.6kbps UL)
- MUX:
Basic Mode
- SMS:
MO/MT Text and PDU modes
Cell broadcast
- Embedded TCP/IP and UDP/IP protocol stack

接口

- SIM Card: 1.8V/3.0V
- Multiple Profiles over USB
- 1 x USB 2.0 Multi-endpoints
- 2 x UART
- MUX Over UART1
- P C M
- I2C
- I2S
- GPIO
- RTC
- HSIC
- A/D

驱动

- Win CE
- Linux 2.6.18 above
- Android 4.2 above

认证

- CCC/RoHS/CE/GCF/FCC/PTCRB/TELEC/RCM/ANATEL

* = 计划中 / 开发中